

MS-001 FEATURES

- MS-001 wafer standalone metrology systems measure wafer deformation
- · Complex wafer processes cause 3 issues
 - Wafer distortion. High-accuracy overlay correction requires multi-point measurement
 - 2. Distortion. Distortion factors are difficult to identify and reduce
 - 3. Process complexity. Optimal alignment measurement can vary for each layer

MS-001 BENEFITS

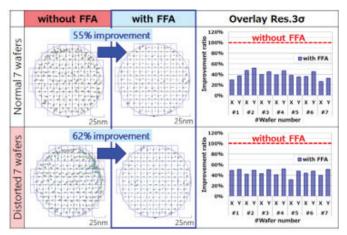
- Offline measurement allows Feed-Forward Alignment (FFA) Correction to improve overlay accuracy
- Offline measurement allows increased sampling and identification of error factors
- Offline measurement allows maximum lithography system utilization and can reduce Cost-of-Ownership
- Enhanced wavelength and alignment mark selectability increases alignment options

High-precision MS-001 overlay measurement system

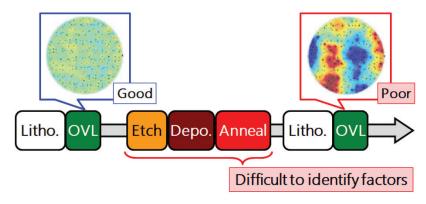
Canon's MS-001 wafer metrology system is capable of premeasuring the position of hundreds of alignment marks on semiconductor wafers in advance of wafer patterning to improve overlay accuracy and lithography system productivity.

Premeasuring the alignment mark positions can result in improved overlay accuracy and reduced alignment measurement time in the lithography process.

The MS-001 allows the majority of alignment measurements to be performed in one batch process, offline from the lithography system. The productivity of the lithography system can be improved by reducing the number of measurements performed during the exposure process.



Overlay improvement using the MS-001 & FFA has been demonstrated



Offline measurement using the MS-001 can help compensate for non-lithography process variability

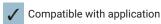
Canon Lithography Systems

Canon Photolithography equipment is designed to help provide exceptional quality, performance, and cost of ownership for your wafer imaging applications.

Canon FPA (Fine Pattern Aligner) Series Nanoimprint, i-line and Deep Ultraviolet (DUV) lithography systems are used in the fabrication and heterogeneous integration of high-tech devices including integrated circuits, hard disk read/write heads, microelectromechanical systems (MEMS) devices, image sensors, displays, power devices and light emitting diodes (LED).

LITHOGRAPHY PRODUCTS & TARGET APPLICATIONS

Lithography Products	Technology	Resolution	Lens Red. Field Size [mm]	Substrate Options [mm]	MRAM	Logic & MPU/GPU	Medical	HDD & SCM	Power & Automotive	Waveguide & RF	Advanced Packaging	Optics & Photonics	MEMS, Sensors & loT	PC & Mobile	5G & Data Centers	Wearables	AR/VR & Display	LED, MicroLED	Artificial Intelligence
FPA-1200NZ2C	Nanoimprint Lithography	≤15 nm	1:1 26 x 33	300	1	1	1	1	1	1	/	1	1	1	1	1	1	1	1
FPA-8000iW	i-line (365 nm) Stepper	≤ 0.8 µm	2:1 55 x 55	510 x 515			1				1	1	1	1	1	1	1	1	1
FPA-3030i6	i-line (365 nm) Stepper	≤ 350 nm	5:1 22 x 22	≤ 200			1	1	1	1	1	1	1	1	1	1		1	1
FPA-3030iWa	i-line (365 nm) Stepper	≤ 0.8 µm	2:1 52 x 52	≤ 200			1	1	1	1	1	1	1	1	1	1	1	1	1
FPA-3030EX6	KrF (248 nm) Stepper	≤ 150 nm	5:1 22 x 22	≤ 200			1	1	1	1	1	1	1	1	1	1		1	1
FPA-5520iV LF2	i-line (365 nm) Stepper	≤ 0.8 µm	2:1 54 x 68	300	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1
FPA-5550iZ2	i-line (365 nm) Stepper	≤ 350 nm ≤ 280 nm (2/3 Ann.)	4:1 26 x 33	200 300	1	1	1	1	1	/	\	1	1	1	1	/	1	1	1
FPA-5510iX	i-line (365 nm) Stepper	≤ 0.5 µm	2:1 50 x 50	300			1	1	1	\	\	1	1	/	\	\	√	/	1
FPA-6300ES6a	KrF (248 nm) Scanner	≤ 100 nm ≤ 90 nm (2/3 Ann.)	4:1 26 x 33	200 300	1	1	1	1	1	1	1	1	1	1	1	1	1		1
FPA-6300ESW	KrF (248 nm) Scanner	≤ 130 nm	3.125:1 33 x 42.2	200 300			1	1	1	√	√	1	1	✓	√	√	√		1
MS-001	Overlay Metrology			300	1	1	1	1	1	1	1	1	1	1	1	1	1	1	✓



All options may not be available on all models. Contact Canon for details.



CANON U.S.A., INC.
Industrial Products Division
3300 North 1st Street • San Jose, CA 95134
Email: semi-info@cusa.canon.com

usa.canon.com/semiconductor (Lithography & ANELVA Products)
usa.canon.com/industrial (Optoelectronics & Motion Control Products)

Canon is registered trademark of Canon Inc. in the United States, and may also be registered trademarks or trademarks in other countries. ANELVA is a registered trademark of Canon Anelva Corporation in the United States, and may also be a registered trademark or trademark in other countries. All other referenced product names and marks are trademarks of their respective owners. Specifications and availability subject to change. Not responsible for typographical errors.

©2024 Canon U.S.A., Inc. All rights reserved.